

TITLE OF THE INVENTION: SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR FORMING THE SAME

Abstract

A semiconductor package assembly, comprising: a semiconductor package comprising: a semiconductor die mounted on a substrate; a pair of interconnection blocks mounted at opposite sides of the semiconductor die; and an encapsulant layer, wherein the pair of interconnection blocks have respective top surfaces exposed and a top surface of the semiconductor die is exposed; and an inductor block mounted on the semiconductor package, comprising: an inductor extending through the insulation body in a horizontal direction, and having a pair of inductor contact pads exposed at a bottom surface of the insulation body, wherein the pair of inductor contact pads are aligned to and electrically coupled to the pair of interconnection blocks; and a thermally conductive coating formed at an outer surface of the insulation body and extending in a vertical direction of the insulation body from the bottom surface to a top surface of the insulation body.

[Fig. 1A]